

**IN THE CLAIMS:**

Please amend claims 1 and 10 as follows:

1. (Twice Amended) A polishing apparatus which imparts relative motion between a layer with a concave portion and a convex portion on a semiconductor wafer and a polishing tool having a plane polishing surface to polish the surface of said workpiece by said plane polishing surface of said polishing tool, comprising:

a dressing tool having a plane dressing surface for forming a surface roughness on the plane polishing surface of said polishing tool;

a first moving means for imparting relative motion in a direction horizontal to the plane polishing surface of said polishing tool between said dressing tool and said polishing tool;

a second moving means for moving said dressing tool in a direction vertical to the plane polishing surface of said polishing tool; and

a control means for permitting to execute movement caused by said first moving means while controlling a position of said second moving means.

10. (Twice Amended) A polishing apparatus which imparts relative motion between a layer with a concave portion and a convex portion and a polishing tool having a plane polishing surface to polish the surface of said workpiece by the plane polishing surface of said polishing tool, comprising:

a dressing tool having a plane dressing surface for forming a surface roughness on the plane polishing surface of said polishing tool; and

a means for inhibiting movement of said dressing tool in a direction vertical to the polishing surface of said polishing tool.

**REMARKS**

Claims 1-11 remain in this application. Claims 1 and 10 are proposed to be amended to better define Applicants so that it more clearly distinguishes over the art. Specifically, the planar nature of the polishing surface and of the dressing tool is called. Applicants note that the claim as previously